

Please add the following new claims:

18. (New) The method of claim 1, further comprising introducing a photoimageable material layer, wherein the dielectric layer comprising the plurality of different material layers is introduced between the substrate and the photoimageable material layer.

19. (New) The method of claim 1, further comprising introducing an etch stop layer between the substrate and the dielectric layer comprising the plurality of different material layers.

20. (New) The method of claim 1, wherein the dielectric layer comprising the plurality of different material layers is introduced between an etch stop layer and a photoimageable material layer.

21. (New) The method of claim 8, further comprising introducing a photoimageable material layer, wherein the dielectric layer comprising the plurality of alternating material layers is introduced between the substrate and the photoimageable material layer.

22. (New) The method of claim 8, further comprising introducing an etch stop layer between the substrate and the dielectric layer comprising the plurality of alternating material layers.

23. (New) The method of claim 8, wherein the dielectric layer comprising the plurality of alternating material layers is introduced between an etch stop layer and a photoimageable material layer.--